

SPECIFICATION

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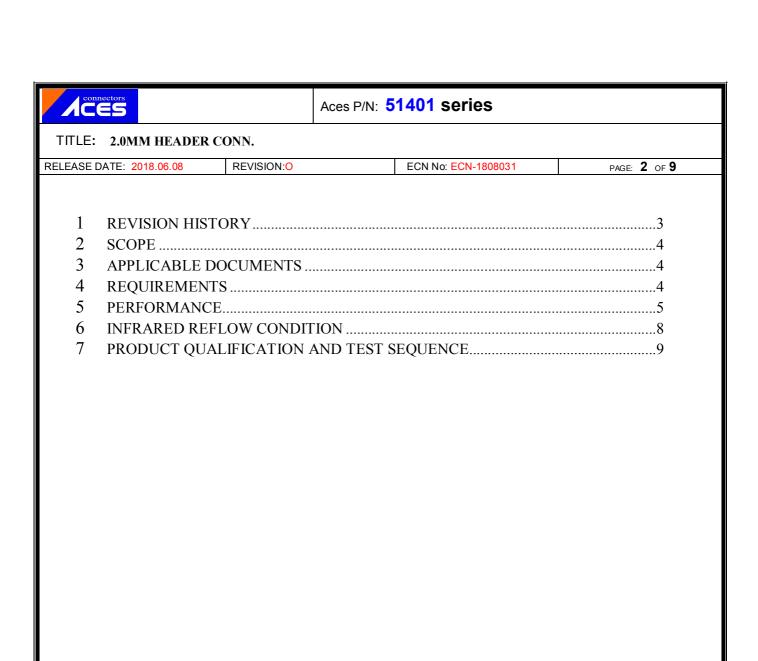
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SPEC. NO.:	PS-5140	01-XXXXX-XXX	REVISION:	<u>O</u>
PRODUCT N	AME:	2.0 MM PITCH HEAI	DER CONN.	
PRODUCT N	0:	51401 series		

PREPARED:	CHECKED:	APPROVED:
Wu, Xiao Guang	Lu, Jing Quan	hsieh, fu yu
DATE: 2018.06.08	DATE: 2018. 06.08	DATE: 2018. 06.08





TITLE: 2.0MM HEADER CONN.

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1 Revision History

Rev.	ECN#	Revision Description	Prepared	Date
O	ECN-1808031	NEW RELEASE	Wu, Xiao Guang	2018.06.08



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2 SCOPE

This specification covers performance, tests and quality requirements for wire to board connector. ACES P/N:51401series.

3 APPLICABLE DOCUMENTS

EIA-364 ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

4.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

- 4.2 Materials and Finish
 - 4.2.1 Contact: High performance copper alloy (Brass)

Finish: (a) Contact Area: Refer to the drawing.

(b) Under plate: Refer to the drawing.

- **4.2.2** Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.3 Ratings
 - 4.3.1Working voltage less than 36 volts (per pin)

4.3.2 Voltage: 200 Volts AC (per pin)

Current: AWG#24 UL 1061 DC 4 Amperes (per pin) total 16A

Operating Temperature : -40°C to +85°C



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5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard			
Examination of Product	Product shall meet requirements of applicable product drawing and specification.				
	ELECTRICAL	pran.			
Item	Requirement	Standard			
Low Level Contact Resistance	$\frac{55 \text{ m } \Omega}{25 \text{ m } \Omega}$ Max. (initial)per contact $\frac{25 \text{ m } \Omega}{25 \text{ m } \Omega}$ Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 10mA Max. (EIA-364-23)			
Insulation Resistance	1000 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)			
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	500 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors.			
		(EIA-364-20) Mate connector: measure the temperature rise at rated current			
Temperature rise	30°C Max. Change allowed	until temperature stable. The ambient condition is still air at 25°C (EIA-364-70 METHOD 1, CONDITION1)			
	MECHANICAL				
Item	Requirement	Standard			
Durability	30 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3 mm/min. (EIA-364-09)			
Mating / Unmating Forces	Mating Force: 700 gf Max./CKT Unmating Force: 150 gf Min./CKT	Operation Speed: 25 ± 3 mm/minute Measure the force required to mate/Unmate connector. (EIA-364-13)			
Terminal / Housing Retention Force 500 gf MIN.		Apply axial pull out force at the speed rate of 25 ± 3 mm/minute. On the terminal assembled in the housing.			



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		Operation Spee	d:				
Contact Retention Force	0.50Kgf Min.	25.4 ± 3 mm/mi	nute. ntact retention force				
Fitting Nail /Housing Retention Force	0.1kgf MIN.	speed rate of 25	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the fitting nail assembled in the housing.				
Vibration	1 μs Max.	The electrical loa 100 mA maximum Subject to a simp having amplitude maximum total expression from 10 to 55 Hz. The entire from 10 to 55 Hz shall be traversed minute. This most for 2 hours in each perpendicular dire (EIA-364-28 Co	en the limits of 10 and e frequency range, and return to 10 Hz, in approximately 1 tion shall be applied h of three mutually ections. ndition I)				
hock (Mechanical)	1 μs Max.	pulses of 11 milli Three shocks in e applied along the perpendicular axe	ne) half-sine shock seconds duration. ach direction shall be three mutually so of the test cks). The electrical all be 100mA contacts.				
	ENVIRONM	IENTAL					
Item	Requiremen		ndard				
Resistance to Reflow Soldering Heat	sistance to Reflow See Product Qualification and		C~180℃, in., 40sec Min. 60℃ Max, 10sec Max.				
Thermal Shock	See Product Qualificatio Sequence Group 4	Mate module ar condition for 5 c 1 cycles: -55 +0/-3 ℃, 30 +85 +3/-0 ℃, 30 (EIA-364-32, tes	minutes) minutes				



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Humidity	See Product Qualification and Test	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature life	See Product Qualification and Test	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)
Salt Spray (Only For Gold Plating)	·	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I)Gold Flash for 8 hours (II) Gold Plating 5u" For 96 hours (EIA-364-26,Test condition B)
Solder ability	Solder able area shall have	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)
Hand Soldering Temperature Resistance	Appearance: No damage	$T \ge 350^{\circ}C$, 3 sec at least.

Note. Flowing Mixed Gas shell be conduct by customer request.

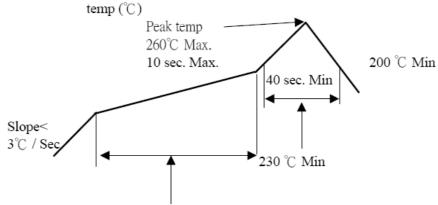
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6 INFRARED REFLOW CONDITION

6.1. Lead-free Process

TEMPERATURE CONDITION GRAPH (TEMPERATURE ON BOARD PATTERN SIDE)



Pre-heat Hold time for $150 \sim 180$ °C is $60 \sim 120$ sec.

connectors

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7 PRODUCT QUALIFICATION AND TEST SEQUENCE

	Test Group									
Test or Examination		2	3	4	5	6	7	8	9	10
		Test Sequence								
Examination of Product				1 . 7	1 . 6	1 \ 4			1	1
Low Level Contact Resistance		1 \ 5	1 \ 4	2 \ 10	2 . 9	2 ` 5			3	
Insulation Resistance				3、9	3 . 8					
Dielectric Withstanding Voltage				4 ` 8	4 . 7					
Temperature rise	1									
Mating / Unmating Forces		2 \ 4								
Durability		3								
Contact Retention Force										
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4